

LH5P8128

CMOS 1M (128K × 8) Pseudo-Static RAM

FEATURES

- 131,072 × 8 bit organization
- Access times (MAX.): 60/80/100 ns
- Cycle times (MIN.): 100/130/160 ns
- Single +5 V power supply
- Power consumption:
Operating: 572/385/275 mW (MAX.)
Standby (CMOS level): 1.1 mW (MAX.)
- TTL compatible I/O
- Available for auto-refresh and self-refresh modes
- 512 refresh cycles/8 ms
- Compatible with standard 1M SRAM pinout
- Packages:
32-pin, 600-mil DIP
32-pin, 525-mil SOP
32-pin, 8 × 20 mm² TSOP (Type I)

DESCRIPTION

The LH5P8128 is a 1M bit Pseudo-Static RAM organized as 131,072 × 8 bits. It is fabricated using silicon-gate CMOS process technology.

A PSRAM uses on-chip refresh circuitry with a DRAM memory cell for pseudo static operation which eliminates external clock inputs, while having the same pinout as industry standard SRAMs. Moreover, due to the functional similarities between PSRAMs and SRAMs, existing 128K × 8 SRAM sockets can be filled with the LH5P8128 with little or no changes. The advantage is the cost savings realized with the lower cost PSRAM.

The LH5P8128 PSRAM has the ability to fill the gap between DRAM and SRAM by offering low cost, low power standby and a simple interface.

PIN CONNECTIONS

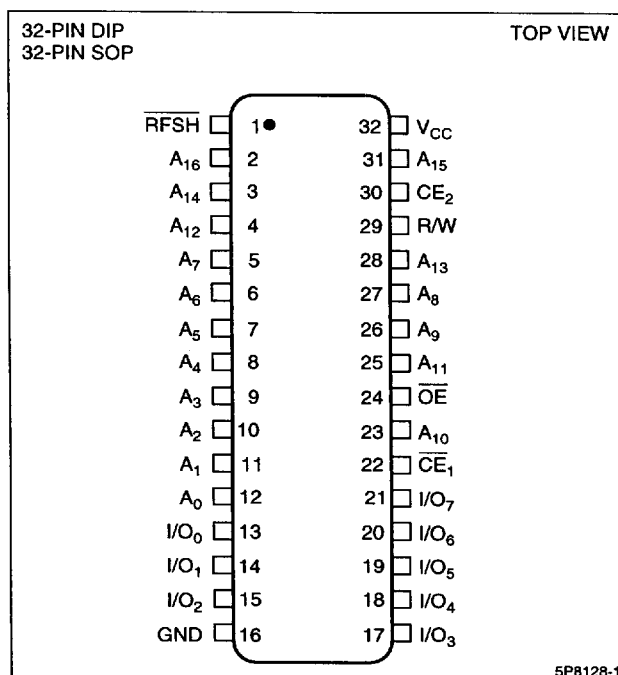
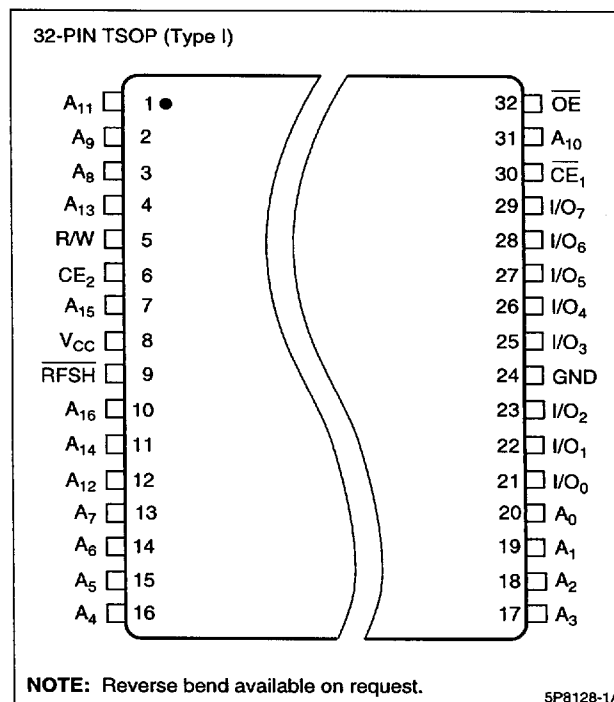


Figure 1. Pin Connections for DIP and SOP Packages



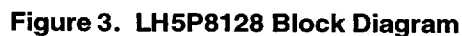
NOTE: Reverse bend available on request.

5P8128-1A

Figure 2. Pin Connections for TSOP Package

SHARP

8180798 0016532 887



SIGNAL	PIN NAME
A ₀ - A ₁₆	Address input
R/W	Read/Write input
OE	Output Enable Input

SIGNAL	PIN NAME
CE ₁ , CE ₂	Chip Enable input
RFSH	Refresh input
I/O ₀ - I/O ₇	Data input/output

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	RATING	UNIT	NOTE
Applied voltage on any pins	V_T	-1.0 to +7.0	V	1
Output short circuit current	I_O	50	mA	
Power dissipation	P_D	600	mW	
Operating temperature	T_{opr}	0 to +70	°C	
Storage temperature	T_{stg}	-55 to +150	°C	

NOTE:

1. The maximum applicable voltage on any pin with respect to GND.

RECOMMENDED OPERATING CONDITIONS ($T_A = 0$ to +70°C)

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply voltage	V_{CC}	4.5	5.0	5.5	V
	GND	0	0	0	V
Input voltage	V_{IH}	2.4		$V_{CC} + 0.3$	V
	V_{IL}	-1.0		0.8	V

CAPACITANCE ($T_A = 0$ to +70°C, $f = 1\text{MHz}$, $V_{CC} = 5.0\text{V} \pm 10\%$)

PARAMETER	CONDITIONS	SYMBOL	MIN.	MAX.	UNIT
Input capacitance	$A_0 - A_{16}$	C_{IN1}		8	pF
	R/W, OE	C_{IN2}		5	pF
	$\overline{CE}_1, CE_2$	C_{IN3}		5	pF
	RFSH	C_{IN4}		5	pF
Input/output capacitance	I/O ₀ - I/O ₇	C_{OUT1}		10	pF

DC CHARACTERISTICS ($T_A = 0$ to +70°C, $V_{CC} = 5.0\text{V} \pm 10\%$)

PARAMETER	SYMBOL	CONDITIONS	MIN.	MAX.	UNIT	NOTE
Operating current	LH5P8128-60	I_{CC1}	$t_{RC} = t_{RC}(\text{MIN})$	104	mA	1, 2
	LH5P8128-80			70		
	LH5P8128-10			50		
Standby current	TTL Input	I_{CC2}		1	mA	1, 3
	CMOS Input			0.2		1, 4
Self-refresh average current	TTL Input	I_{CC3}		1	mA	1, 5
	CMOS Input			0.2		1, 6
Input leakage current	I_{LI}	$0\text{V} \leq V_{IN} \leq 6.5\text{V}$ 0V except on test pins	-10	10	μA	
I/O leakage current	I_{LO}	$0\text{V} \leq V_{OUT} \leq V_{CC} + 0.3\text{V}$ Output in high-impedance state	-10	10	μA	
Output HIGH voltage	V_{OH}	$I_{OUT} = -1\text{mA}$	2.4		V	
Output LOW voltage	V_{OL}	$I_{OUT} = 4\text{mA}$		0.4	V	

NOTES:

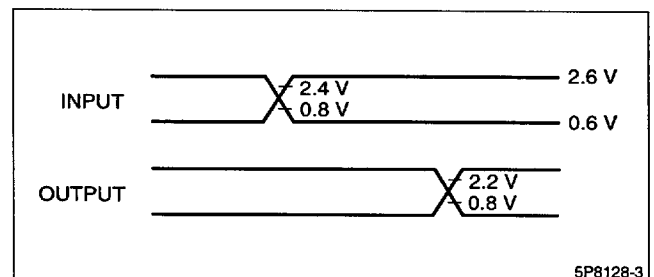
1. Specified values are with outputs open.
2. Depends on the cycle time.
3. $\overline{CE}_1 = V_{IH}$, $RFSH = V_{IH}$
4. $\overline{CE}_1 = V_{CC} - 0.2\text{V}$, $RFSH = V_{CC} - 0.2\text{V}$
5. $\overline{CE}_1 = V_{IH}$, $RFSH = V_{IL}$
6. $\overline{CE}_1 = V_{CC} - 0.2\text{V}$, $RFSH = 0.2\text{V}$

AC ELECTRICAL CHARACTERISTICS ^{1,2,3} ($T_A = 0$ to $+70^\circ\text{C}$, $V_{CC} = 5.0\text{ V} \pm 10\%$)

PARAMETER	SYMBOL	LH5P8128-60		LH5P8128-80		LH5P8128-10		UNIT	NOTE
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Random read, write cycle time	t_{RC}	100		130		160		ns	
Read modify write cycle time	t_{RMW}	165		195		235		ns	
CE pulse width	t_{CE}	60	10,000	80	10,000	100	10,000	ns	
CE precharge time	t_P	40		40		50		ns	
Address setup time	t_{AS}	0		0		0		ns	4
Address hold time	t_{AH}	15		20		25		ns	4
Read command setup time	t_{RCS}	0		0		0		ns	
Read command hold time	t_{RCH}	0		0		0		ns	
CE access time	t_{CEA}		60		80		100	ns	5
OE access time	t_{OEA}		25		30		35	ns	5
CE to output in Low-Z	t_{CLZ}	20		20		20		ns	
OE to output in Low-Z	t_{OLZ}	0		0		0		ns	
Output enable from end of write	t_{WLZ}	0		0		0		ns	
Chip disable to output in High-Z	t_{CHZ}		20		25		30	ns	
Output disable to output in High-Z	t_{OHZ}		20		25		30	ns	
Write enable to output in High-Z	t_{WHZ}		20		25		30	ns	
OE setup time	t_{OES}	0		0		0		ns	
OE hold time	t_{OEH}	10		10		10		ns	
Write command pulse width	t_{WP}	30		30		30		ns	
Write command setup time	t_{WCS}	30		30		30		ns	
Write command hold time	t_{WCH}	40		50		60		ns	
Data setup time from write	t_{DSW}	25		30		35		ns	6
Data setup time from CE	t_{DSC}	25		30		35		ns	6
Data hold time from write	t_{DHW}	0		0		0		ns	6
Data hold time from CE	t_{DHC}	0		0		0		ns	6
Transition time (rise and fall)	t_T	3	35	3	35	3	35	ns	
Refresh time interval	t_{REF}		8		8		8	ms	
Refresh command hold time	t_{RHC}	15		15		15		ns	
Auto refresh cycle time	t_{FC}	100		130		160		ns	
Refresh delay time from CE	t_{RFD}	30		40		50		ns	
Refresh pulse width (Auto refresh)	t_{FAP}	30	8,000	30	8,000	30	8,000	ns	
Refresh precharge time (Auto refresh)	t_{FP}	30		30		30		ns	
Refresh pulse width (Self refresh)	t_{FAS}	8,000		8,000		8,000		ns	
CE delay time from refresh precharge (Self refresh)	t_{FRS}	140		160		190		ns	

NOTES:

1. In order to initialize the circuit, $\overline{CE}_1$ should be kept at V_{IH} or CE_2 should be kept at V_{IL} for 100 μs after power-up, followed by at least 8 dummy cycles.
2. AC characteristics are measured at $t_T = 5\text{ ns}$.
3. AC characteristics are measured at the following condition (see figure at right).
4. Address is latched at the negative edge of $\overline{CE}_1$ or at the positive edge of CE_2 .
5. Measured with a load equivalent to 2TTL + 100 pF.
6. Data is latched at the positive edge of W/R or at the positive edge of CE_1 or at the negative edge of CE_2 .



5P8128-3

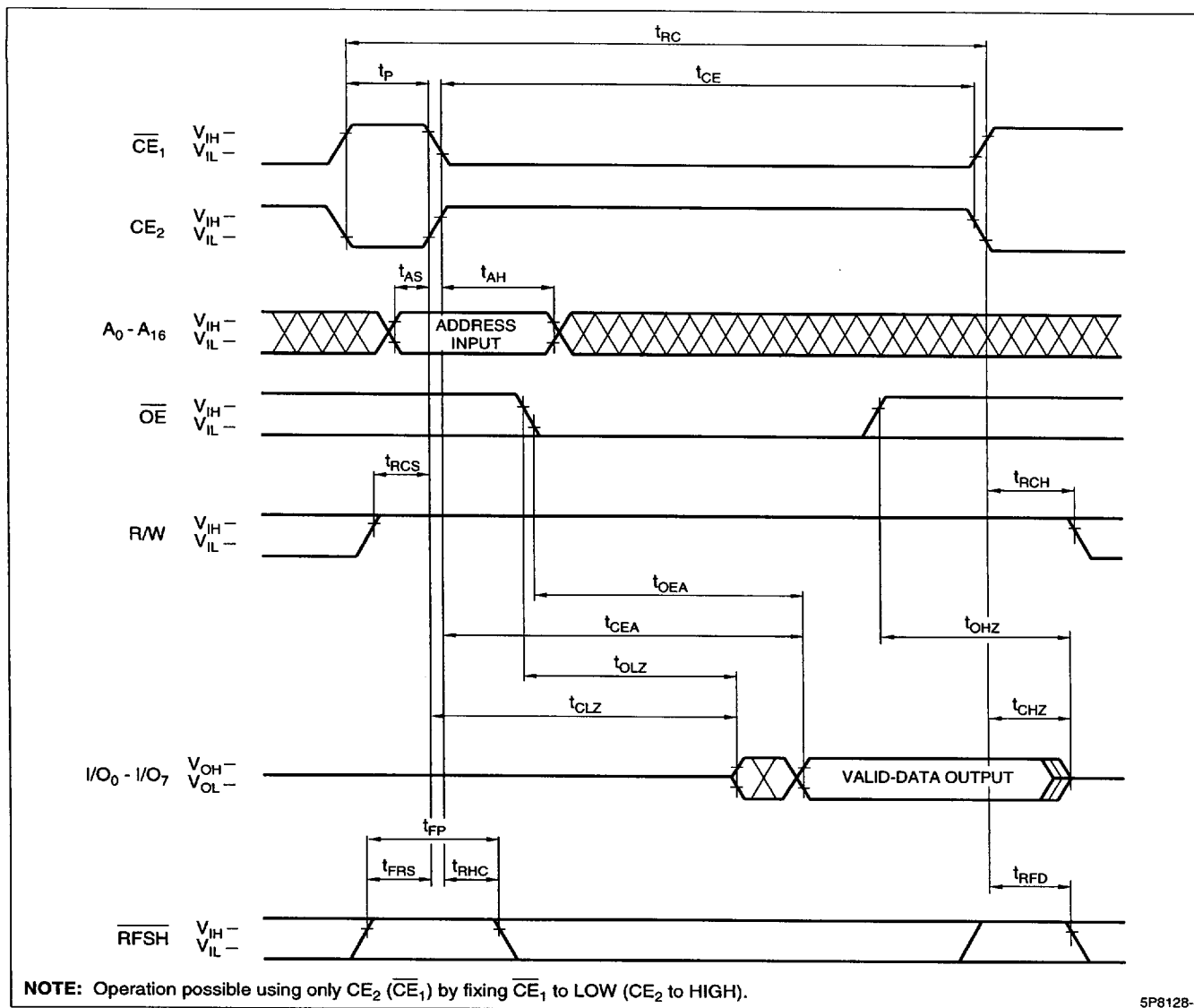
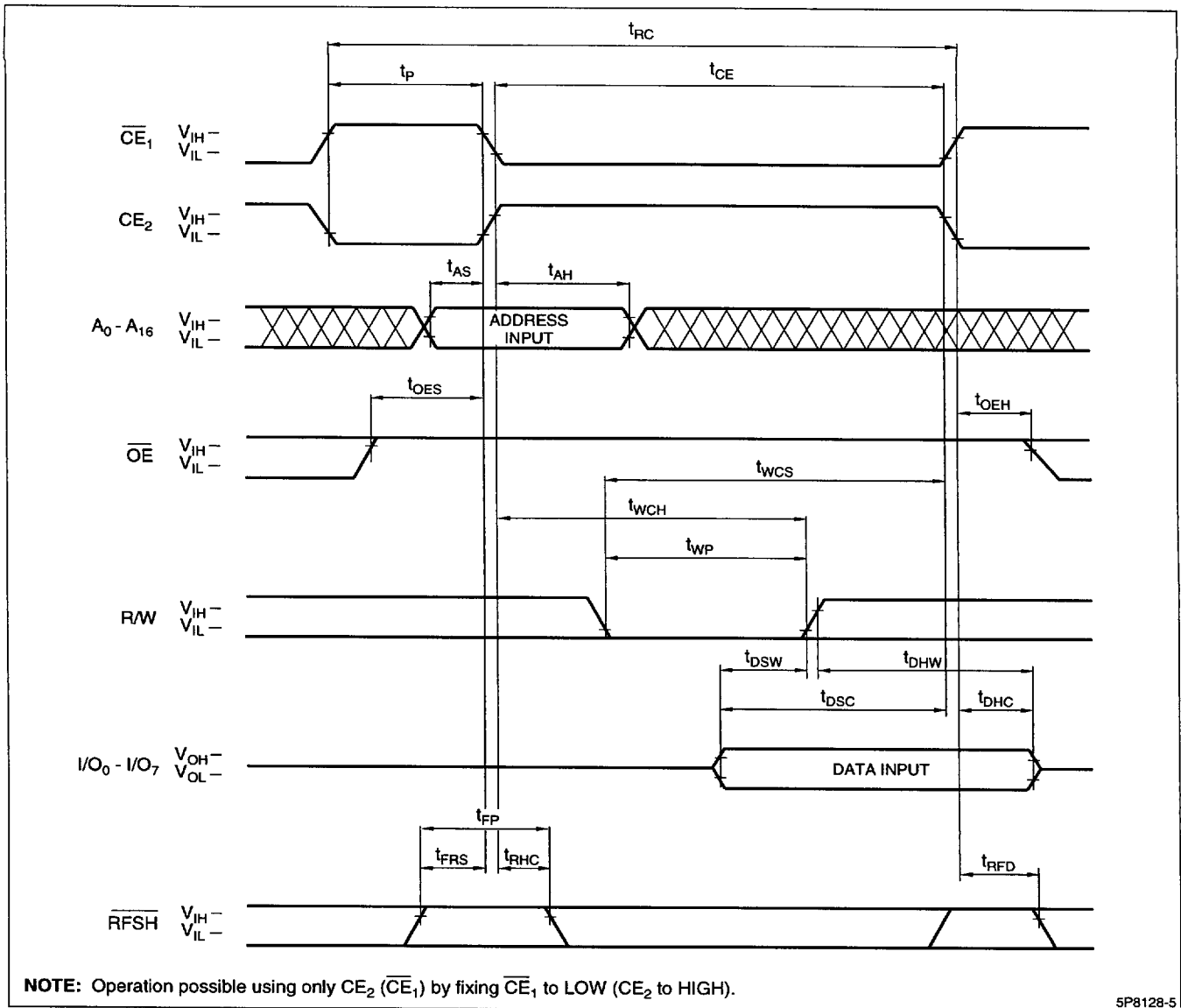
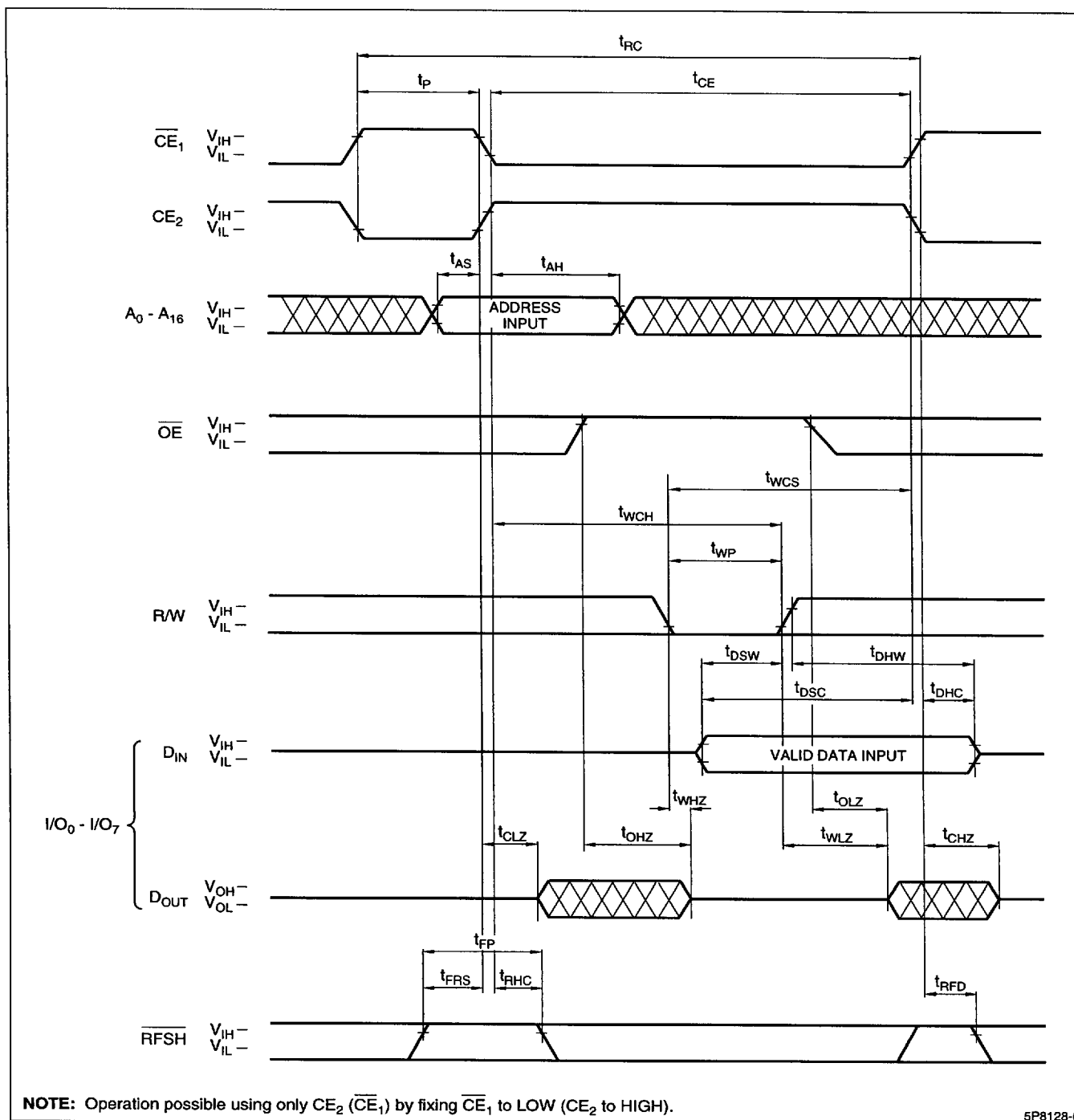


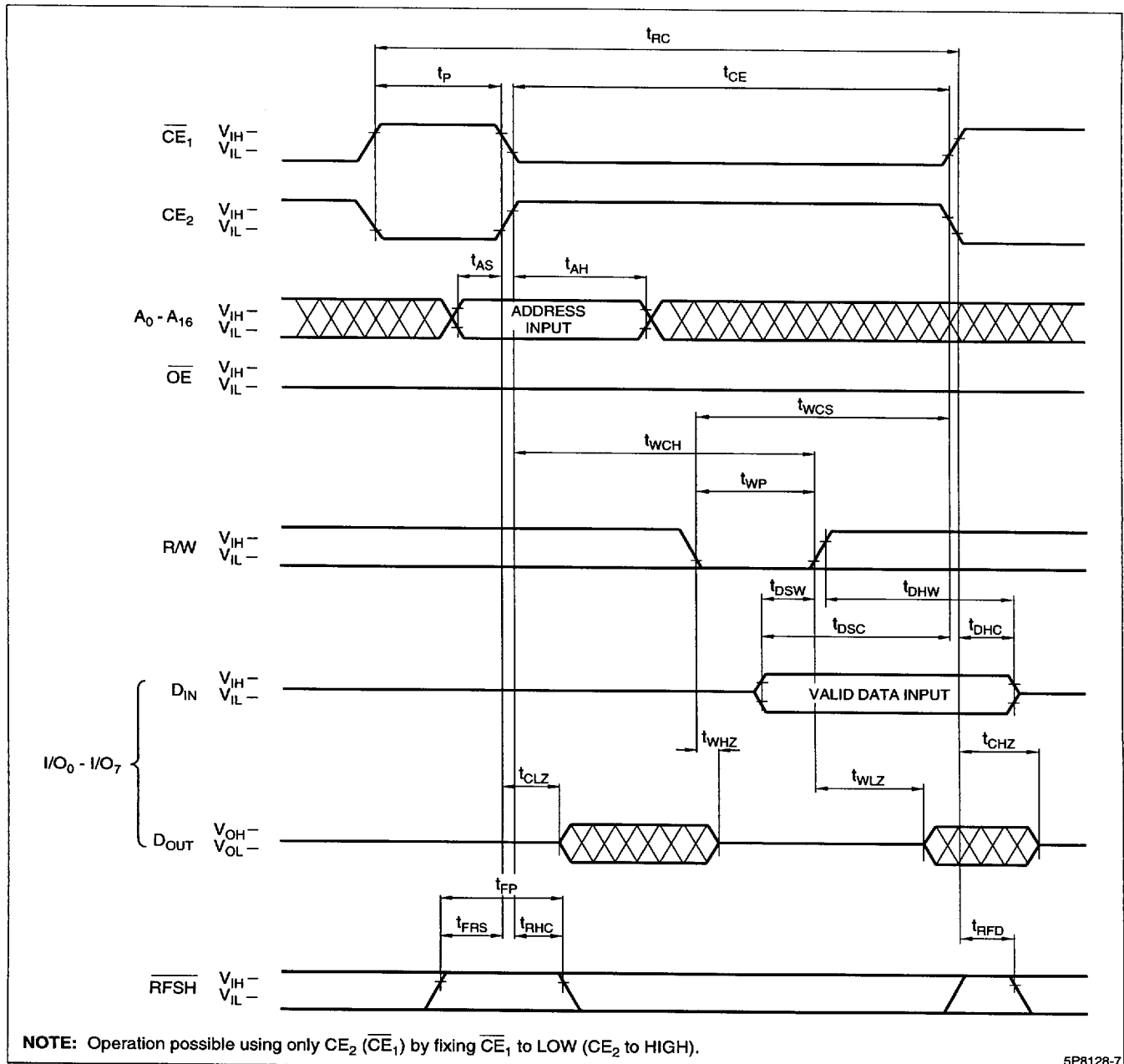
Figure 4. Read Cycle

Figure 5. Write Cycle 1 ($\overline{OE} = \text{HIGH}$)



5P8128-6

Figure 6. Write Cycle 2 (OE Clock)

Figure 7. Write Cycle 3 ($\overline{OE} = \text{LOW}$)

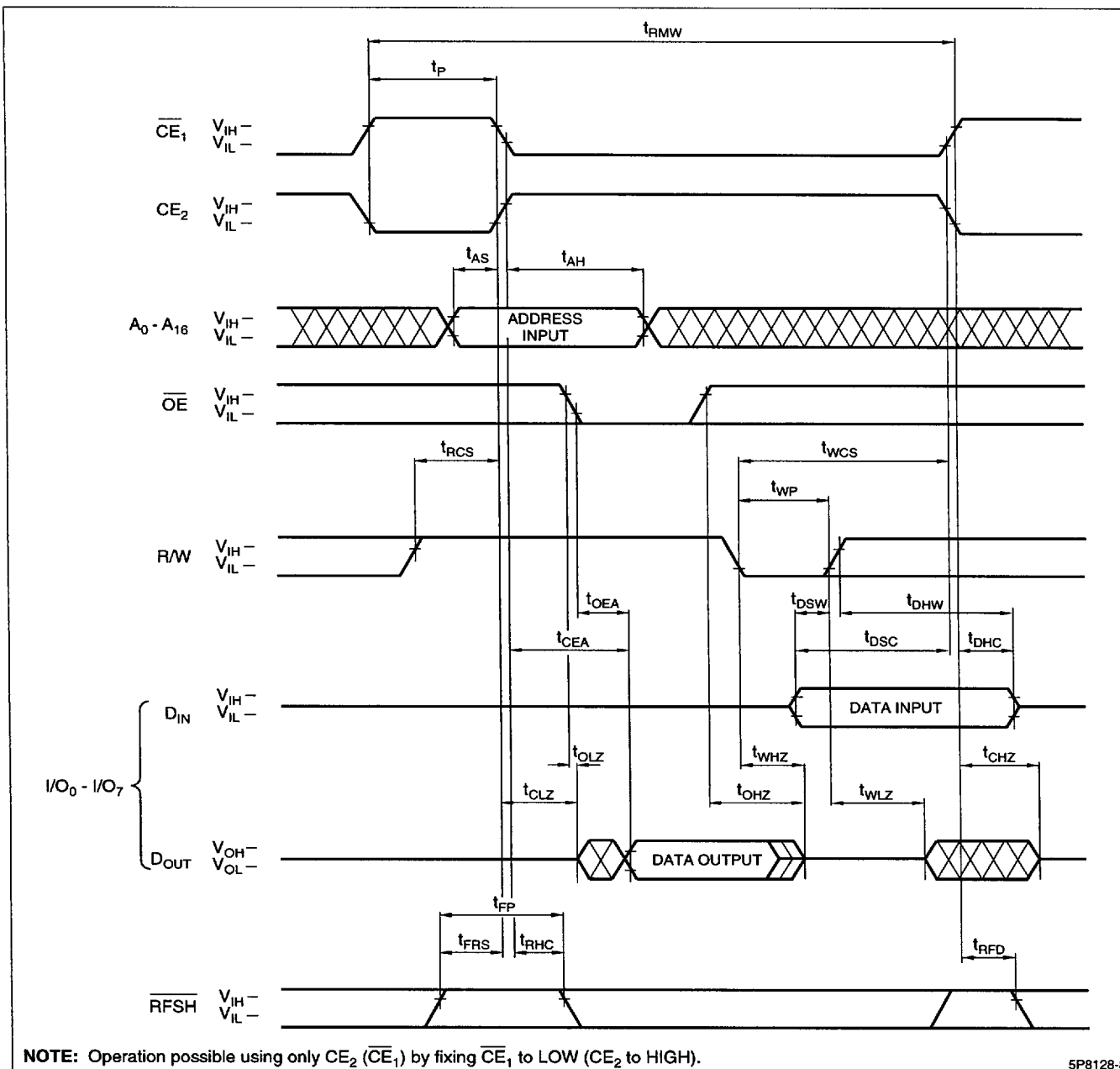


Figure 8. Read-Modify-Write Cycle

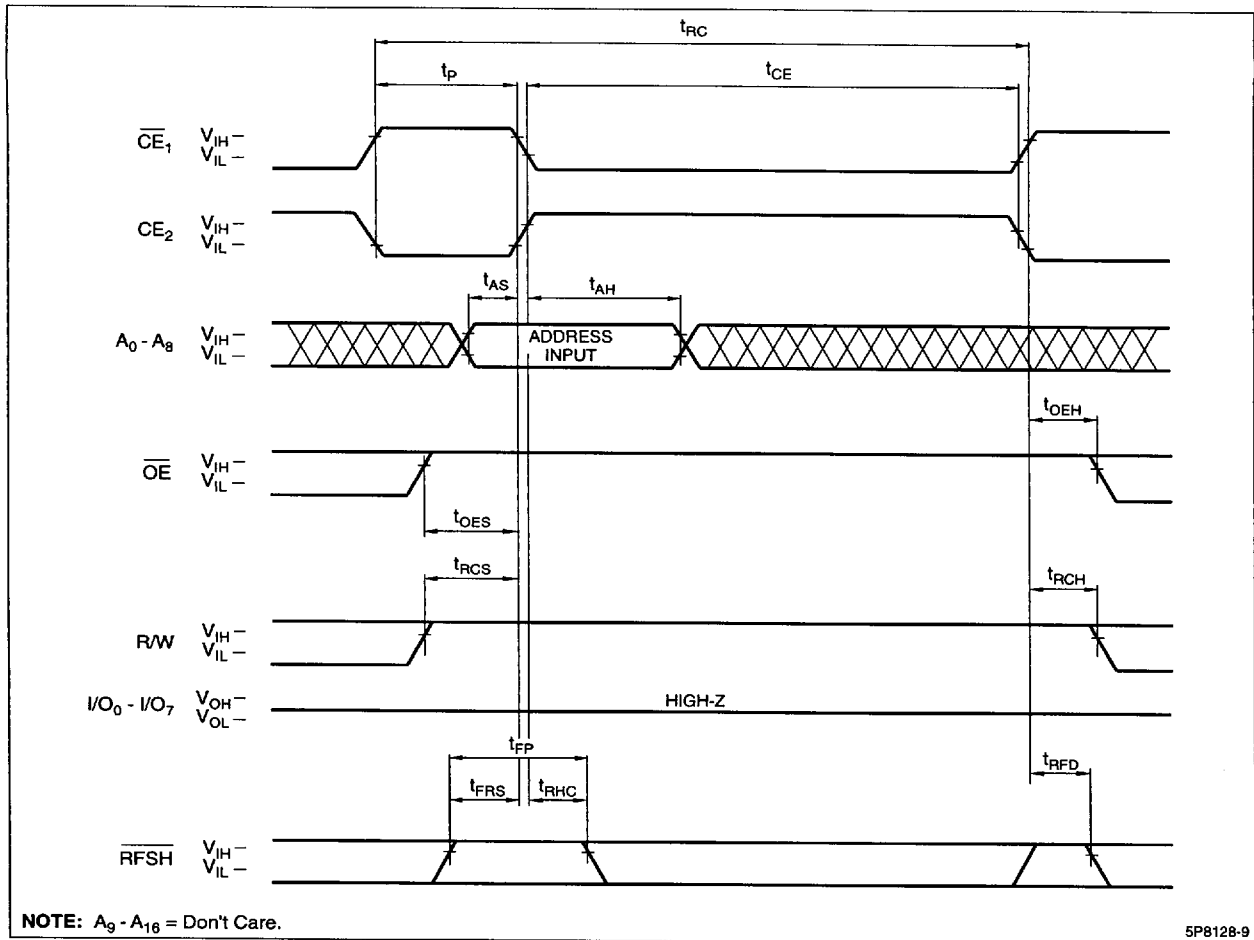


Figure 9. CE Only Refresh

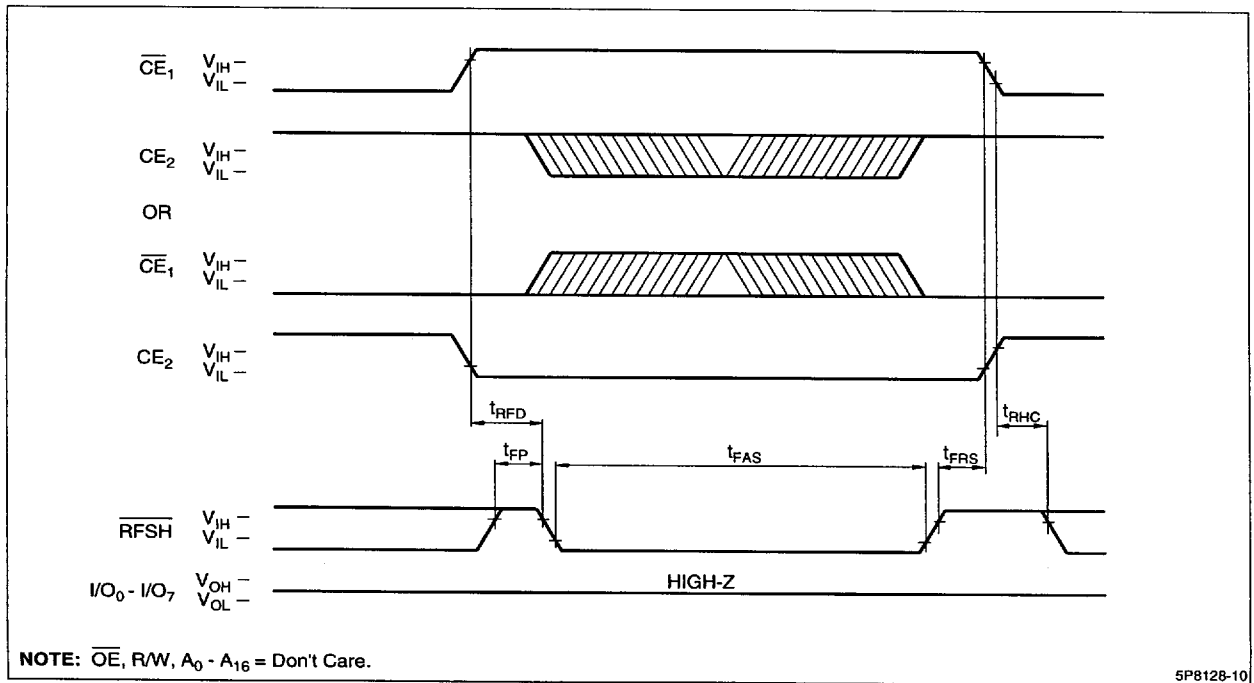
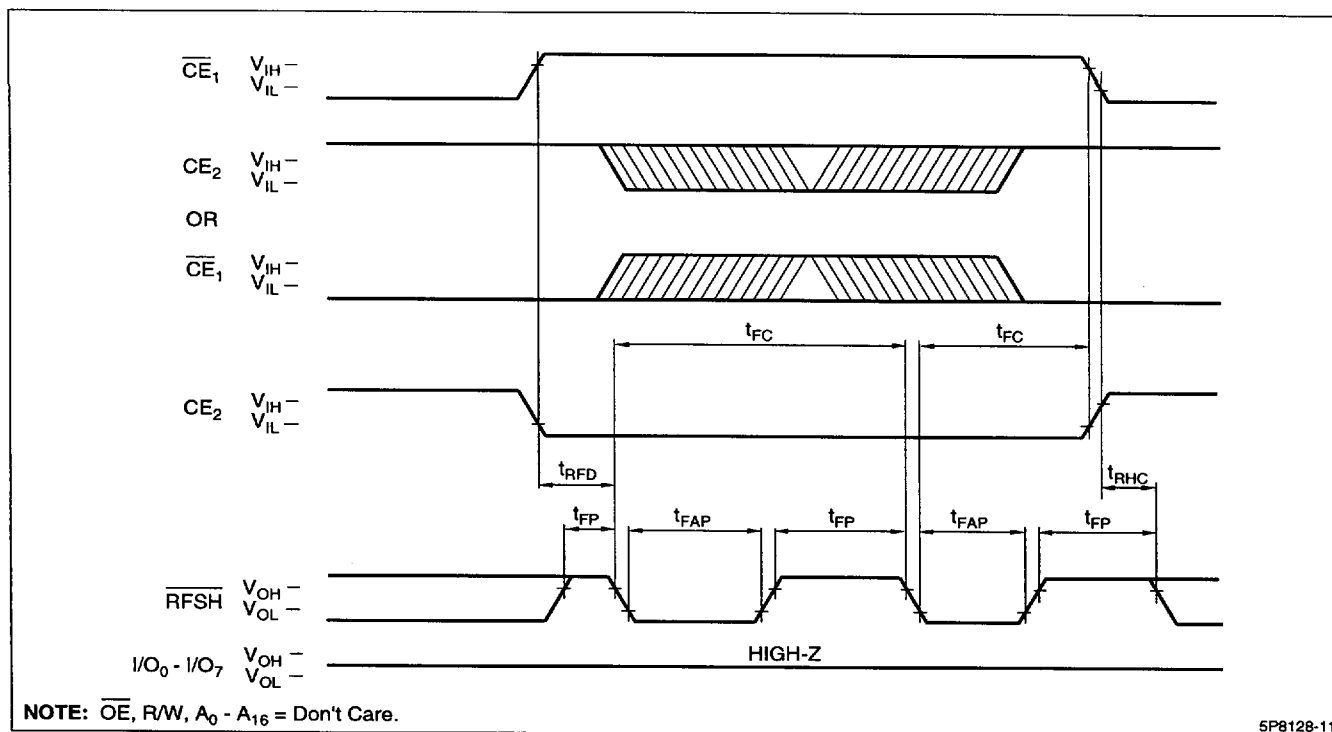


Figure 10. Self Refresh Cycle

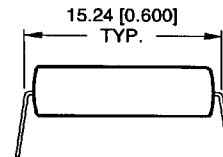
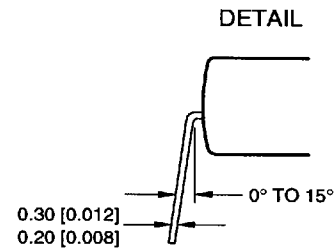
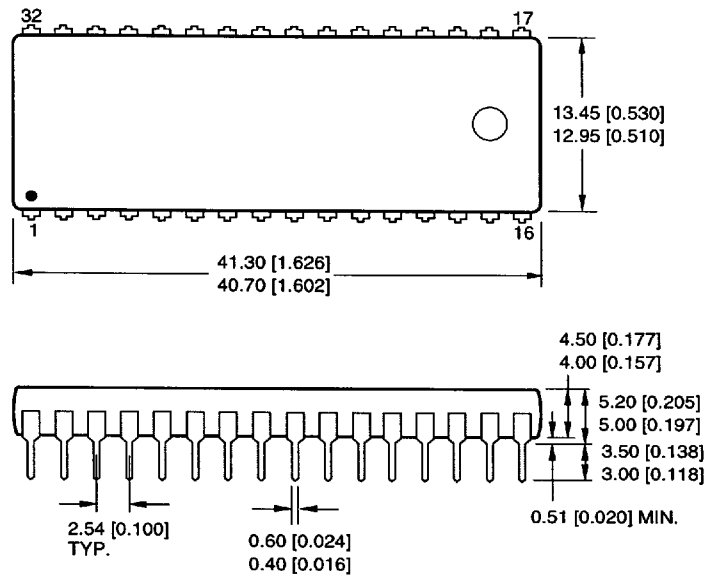


5P8128-11

Figure 11. Auto Refresh Cycle

PACKAGE DIAGRAMS

32DIP (DIP032-P-0600)

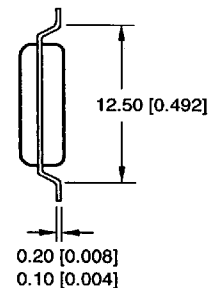
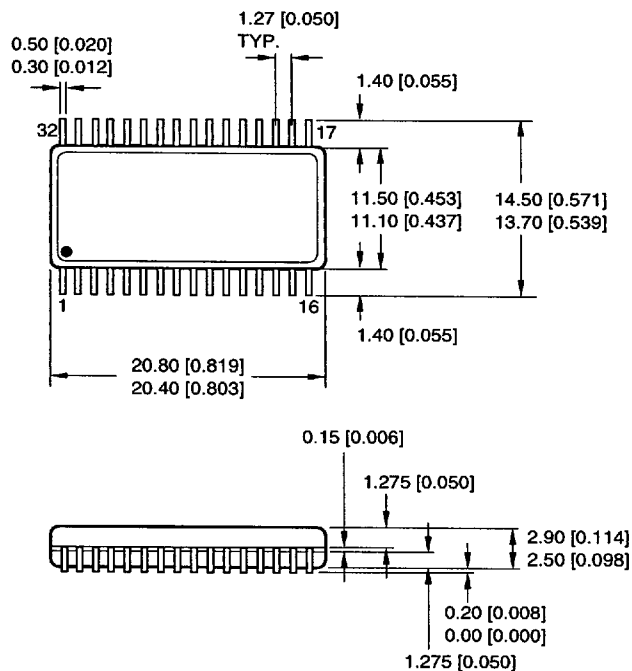


DIMENSIONS IN MM [INCHES] MAXIMUM LIMIT
MINIMUM LIMIT

32DIP

32-pin, 600-mil DIP

32SOP (SOP032-P-0525)



DIMENSIONS IN MM [INCHES] MAXIMUM LIMIT
MINIMUM LIMIT

32SOP

32-pin, 525-mil SOP

Figure 1: Dimensions of the 16-pin DIP package. The figure includes three views: a top view, a side view, and a cross-sectional view. The top view shows a square package with pins 1-16 on the bottom and 17-32 on the top. Dimensions include pin pitch (0.30 [0.012]), pin width (0.10 [0.004]), and overall width (8.20 [0.323]). The side view shows a height of 19.00 [0.748] and a pin height of 1.20 [0.047] MAX. The cross-sectional view shows a package thickness of 0.15 [0.006] and a lead thickness of 0.20 [0.008].

32TSOP

32-pin, 8 × 20 mm² TSOP (Type I)

<u>LH5P8128</u>	<u>X</u>	<u>- ##</u>	
Device Type	Package	Speed	
		60 60 80 80 10 100	Access Time (ns)
		Blank 32-pin, 600-mil DIP (DIP032-P-0600) N 32-pin, 525-mil SOP (SOP032-P-0525) T 32-pin, 8 x 20 mm² TSOP (Type I) (TSOP032-P-0820) TR 32-pin, 8 x 20 mm² TSOP (Type I) Reverse bend (TSOP032-P-0820)	
		CMOS 1M (128K x 8) Pseudo-Static RAM	

Example: LH5P8128N-60 (CMOS 1M (128K x 8) Pseudo-Static RAM, 60 ns, 32-pin, 525-mil SOP)